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65 Silver - 20 Copper-15 Palladium

Physical Properties of Bulk Solder

Solder Alloy Composition 65Ag20Cu15Pd (weight per cent)

Solidus temperature 850°C (1562°F)
Liquidus temperature 900°C (1652°F)
Density 10.33 kg/l
Yield strength 379 MPa
Tensile strength 448 MPa
Elongation 23%

Thermal conductivity 98 W/(m.K)

Thermal Coefficient of Expansion 19 x 10⁻⁶ K⁻¹ (estimate)

Electrical Conductivity $13x10^6/\Omega$ m Electrical Resistivity $7.8 \mu\Omega$ cm

Typical impurity levels for electronic grade/ vacuum tube grade are less then:

Pb: 0.002 Zn: 0.002 P: 0.020

Cd: 0.002 C: 0.005

Volatile elements each 0.002 % max. Other elements each 0.005% max. Total other elements 0.010% max.

AgCu-alloys are generally used to join, silver, copper and nickel base alloys in reducing or inert atmospheres or vacuum. They are also widely used to join metalized ceramics to metals in vacuum. This assumes reasonably-clean brazing surfaces or controlled atmosphere during the brazing cycle. If and when the components are slightly oxidized, a combination with higher temperatures and/or longer brazing temperatures is required.

Joint clearance is recommended at 0.002" - .005" (50-127µm).

During remelting joints on either copper- or silver-base alloys, the braze exhibits decreased fluidity and an increased remelt temperature, due to the solution of either silver or copper in the eutectic. Brazing time and temperature should be minimized to prevent excessive diffusion and erosion of the base metal. AgCu-based filler materials have limited wetting ability on iron and/or nickel base alloys. The wetting it does have is derived primarily from its copper and palladium content. Both nickel and iron have practically no solubility in silver. The addition of palladium to the AgCu-alloy enables good wetting to Ni and Ni-alloys, Kovar, (low-) alloyed steels, tool steels and Stainless steels. It further prevents intermetallic building in the joint area

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